SCLS008C - MARCH 1984 - REVISED MARCH 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- Inputs Are TTL-Voltage Compatible
- High-Current 3-State Outputs Interface Directly With System Bus or Can Drive Up To 15 LSTTL Loads
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)

SN54HCT540 . . . J PACKAGE SN74HCT540 . . . DW OR N PACKAGE (TOP VIEW) 20 VCC OE1 19 0E2 A1 2 A2 3 18 Y1 A3 4 17 Y2 A4 5 16 Y3 15 🛛 Y4 A5 Π6 A6 14 Y5 Π7 13 Y6 A7 8 12 Y7 A8 9 GND 10 11 Y8

description/ordering information

These octal buffers and line drivers are designed to have the performance of the 'HCT240 devices and a pinout with inputs and outputs on opposite sides of the package. This arrangement greatly facilitates printed circuit board layout.

The 3-state control gate is a 2-input NOR. If either output-enable ($\overline{OE1}$ or $\overline{OE2}$) input is high, all eight outputs are in the high-impedance state. The 'HCT540 devices provide inverted data at the outputs.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

TA	PACKAG	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N Tube		SN74HCT540N	SN74HCT540N
–40°C to 85°C		Tube	SN74HCT540DW	HCT540
	SOIC – DW	Tape and reel	SN74HCT540DWR	HC1540
–55°C to 125°C	CDIP – J	Tube	SNJ54HCT540J	SNJ54HCT540J

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each buffer/driver)

	INPUTS	OUTPUT	
OE1	OE2	Α	Y
L	L	L	Н
L	L	Н	L
н	Х	Х	Z
Х	Н	Х	Z



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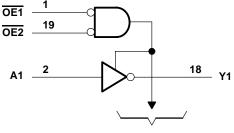
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	54HCT5	40	SN74HCT540		UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V_{CC} = 4.5 V to 5.5 V	2			2			V
VIL	Low-level input voltage	$V_{CC} = 4.5 V \text{ to } 5.5 V$			0.8			0.8	V
VI	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
tt	Input transition (rise and fall) time				500			500	ns
Т _А	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		Vee	T _A = 25°C			SN54HCT540		SN74HCT540		UNIT
PARAMETER			Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
VOH	$V_{1} = V_{1} + or V_{2}$	I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OH} = –6 mA	4.5 V	3.98	4.3		3.7		3.84		
Voi	$V_{OL} \qquad V_{I} = V_{IH} \text{ or } V_{IL} \qquad \frac{I_{OL} = 20 \ \mu A}{I_{OL} = 6 \ m A} \qquad 4.3$	V _{OI} V _I = V _I H or V _I I _{OL} = 20 μA 4.5 V		0.001	0.1		0.1		0.1	V	
VOL		$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	v
lj	$V_I = V_{CC} \text{ or } 0$		5.5 V		±0.1	±100		±1000		±1000	nA
I _{OZ}	$V_{O} = V_{CC} \text{ or } 0,$	$V_I = V_{IH} \text{ or } V_{IL}$	5.5 V		±0.01	±0.5		±10		±5	μΑ
lcc	$V_{I} = V_{CC} \text{ or } 0,$	I _O = 0	5.5 V			8		160		80	μΑ
∆lCC‡	One input at 0.5 V Other inputs at 0 o		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	Vee	Т	₄ = 25°C	;	SN54HC	CT540	SN74H	CT540	UNIT
PARAMETER	(INPUT)		Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
.	А	Y	4.5 V		13	20		30		25	ns
^t pd	A		5.5 V		12	18		27		23	
+	ŌĒ	Y	4.5 V		20	30		45		38	20
t _{en}			5.5 V		18	27		41		34	ns
*	ŌĒ	Y	4.5 V		19	30		45		38	2
^t dis			5.5 V		18	27		41		34	ns
tt		V	4.5 V		8	12		18		15	ns
		1	5.5 V		7	11		16		14	115

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

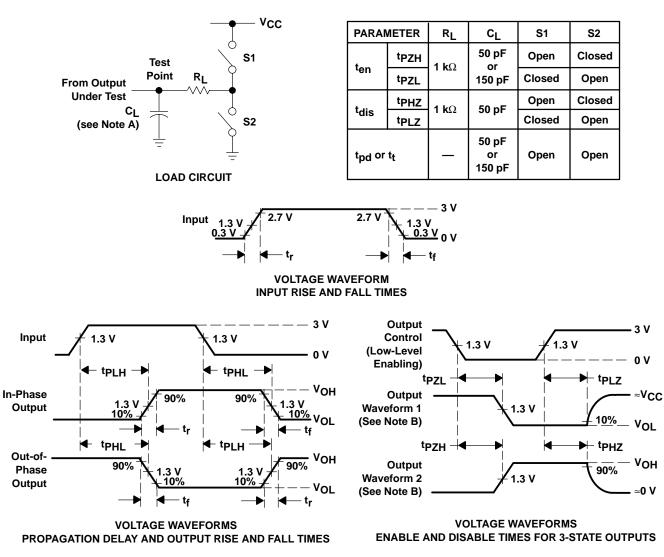
PARAMETER	FROM	то	Vee	Т	ן = 25°C	;	SN54H	CT540	SN74H	CT540	UNIT
	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t pd	А	Y	4.5 V		20	30		45		38	200
			5.5 V		19	27		41		34	ns
ten	ŌĒ	Y	4.5 V		26	40		60		50	-
			5.5 V		25	36		54		45	ns
tt		Y	4.5 V		17	42		63		53	00
			5.5 V		14	38		57		48	ns

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per buffer/driver	No load	35	pF



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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. CL includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tp71 and tp7H are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - Figure 1. Load Circuit and Voltage Waveforms



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

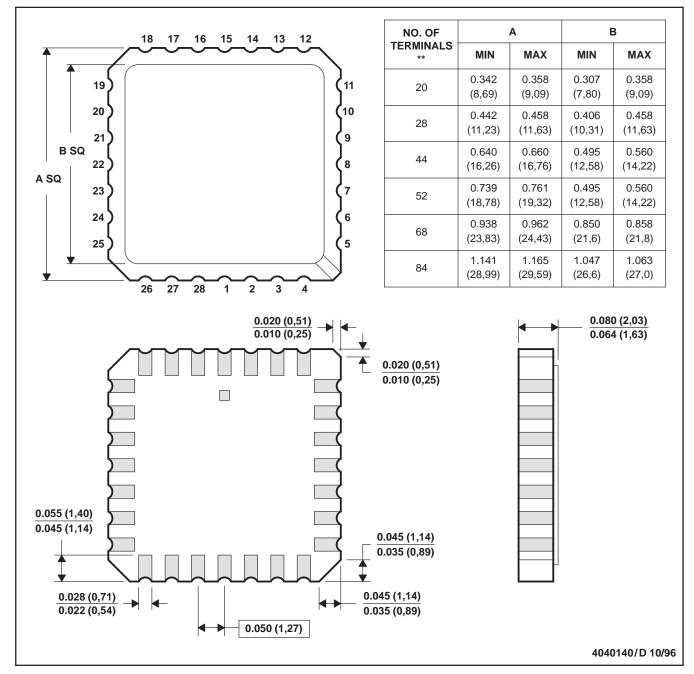
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MLCC006B - OCTOBER 1996

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004

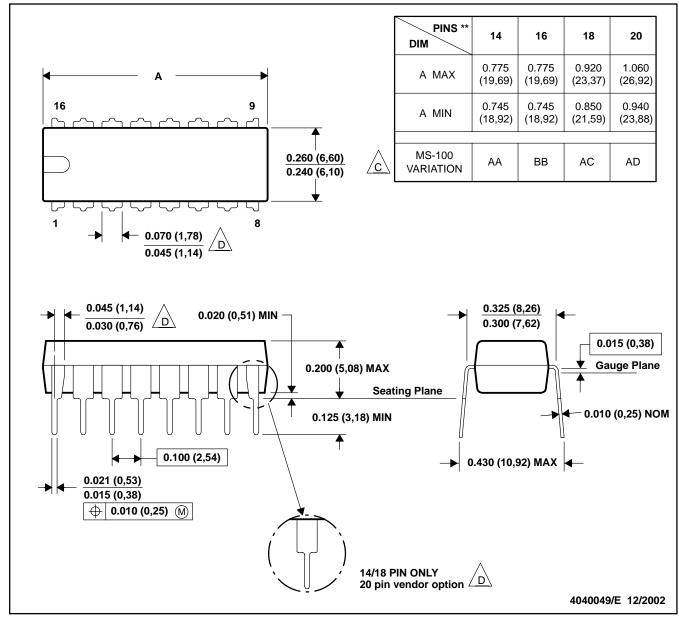


MPDI002C - JANUARY 1995 - REVISED DECEMBER 20002

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

/д.

B. This drawing is subject to change without notice.

/C Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

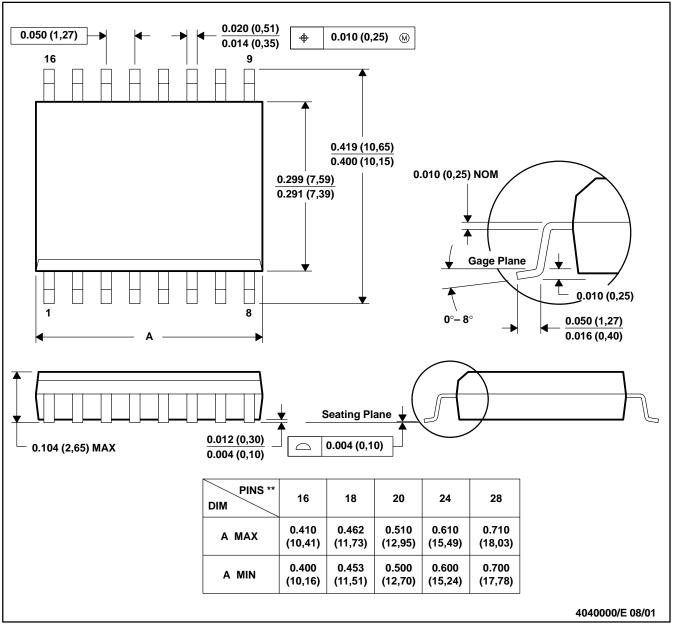


MECHANICAL DATA

MSOI003E - JANUARY 1995 - REVISED SEPTEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

DW (R-PDSO-G**) 16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



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Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

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